

IN THE CLAIMS

Please substitute claims 1-17 with the following:

1. (Currently Amended) A solid-state image pickup device comprising:
a circuit board having ~~an~~ a first opening;
a sensor package with a second opening, in which a chip of a solid-state image pickup element with a light-receiving surface is placed, the sensor package disposed at one surface of the circuit board so that the light-receiving surface of the chip of the solid-state image pickup element opposes the said first opening of the circuit board;
a seal covering entirely said second opening and adhered to the sensor package for sealing in the solid-state image pickup element; and
an optical unit disposed at the other surface of the circuit board so that incident light is focused on the light-receiving surface;
wherein,
the circuit board is disposed between the sensor package and the optical unit,
the circuit board has substantially flat surfaces,
the solid-state image pickup element is disposed on a surface of the sensor package, and
the seal is placed within the said first opening of the circuit board.
2. (Original) A solid-state image pickup device according to Claim 1, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.
3. (Original) A solid-state image pickup device according to Claim 1, wherein the solid-state image pickup element has a signal processing function.

4. (Original) A solid-state image pickup device according to Claim 1, wherein the circuit board is connected to an external device without a connector.

5. (Currently Amended) A method of producing a solid-state image pickup device comprising the steps of:

providing a circuit board with ~~an~~ a first opening;

joining a sensor package with a second opening, in which a chip of a solid-state image pickup element is placed ~~has been previously sealed~~, to one surface of the circuit board so that a light-receiving surface of the chip of the solid-state image pickup element opposes the said first opening of the circuit board;

placing a seal covering entirely said second opening of the sensor package, within said first opening of the circuit board, for sealing in the solid-state image pickup element; and

disposing and joining an optical unit at and to the other surface of the circuit board so that incident light is focused on the light-receiving surface,

wherein,

the circuit board is disposed between the sensor package and the optical unit,

the circuit board has substantially flat surfaces, and

the solid-state image pickup element is disposed on a surface of the sensor package.

6. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.

7. (Original) A method of producing a solid-state image pickup device according to
Claim 5, wherein the solid-state image pickup element has a signal processing function.

8. (Original) A method of producing a solid-state image pickup device according to
Claim 5, wherein the circuit board is connected to an external device without a connector.

9. (Previously Presented) A solid-state image pickup device according to Claim 1,
wherein the seal is a glass seal.

10-17. (Cancelled).

18. (New) A solid-state image pickup device according to Claim 1, wherein said
sensor package is electrically connected with said circuit board via die bonding.

19. (New) A method of producing a solid-state image pickup device according to
Claim 5, wherein said sensor package is electrically connected with said circuit board via die
bonding.